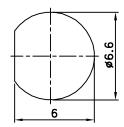
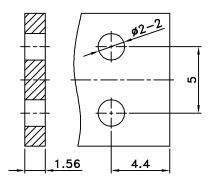
REV	DESCRIPTION\PER REQUEST	DRAWN	DATE



RECOMMENDED MOUNTING HOLE



PCB MOUNTING HOLES

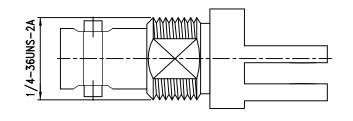
11.25 REF

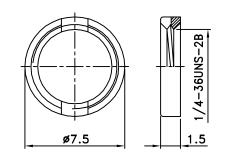
20.1 REF

20.1 REF

SQ 7.5

4.5





1.60

1.60^{±0.03}

-STAKE 4 POINTS

NO	Description	Q'ty	Material	Finish	
1	Body	1	Brass	Gold	ŀ
2	Body	1	Brass	Gold	ŀ
3	Pin	1	Beryllium	Gold	ľ
4	Dielectric	1	Teflon	None	
5	Nut	1	Brass	Gold	L

PART NO.			* MAJ	OR DIM	ENSION	
	361EHI	D704			THERV	
APPROVED		DATE	NOTE		LERAN	
		08/14/12			-6=± 30=±	
CHECKED		DATE	1		$20=\pm$	
		08/14/12] 1		15=±	
DRAWN		DATE	ANGLES=±1°			
	Wen	08/14/12	SCALE	4/1	UNIT	mm

: S	Bomar Interconnect Products,Inc				
	TITLE HIGH DENSITY BNC E-SNAP	JACK			
	DRAWING NO. ASHDBNC-41002-2-75-TGG	REV C			
m	FILE NO. W:\?~\AS\ASHDBNC\ASHDBNC-41002-2-75-TGG Boma	r->20120814			

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Winchester Interconnect: 361EHD704